

#### Abstract of the Disclosure

A resin-sealed electronic circuit apparatus capable of maintaining a high heat-dissipating property and packaging density in applications where high hermetic-sealing property and durability are required. The electronic circuit apparatus comprises at least two wiring circuit boards 12 and 13 on which electronic components are mounted. The wiring circuit boards 12 and 13 are fixed to a heat sink 14 having a high heat conductivity via an adhesive 9 and 10. The entirety of the wiring circuit boards 12 and 13 and heat sink 14, as well as a part of an external connection terminal 8 are hermetically sealed and integrally molded by a thermosetting resin composition 7. The electronic circuit apparatus is small and highly reliable and can be provided at low cost.